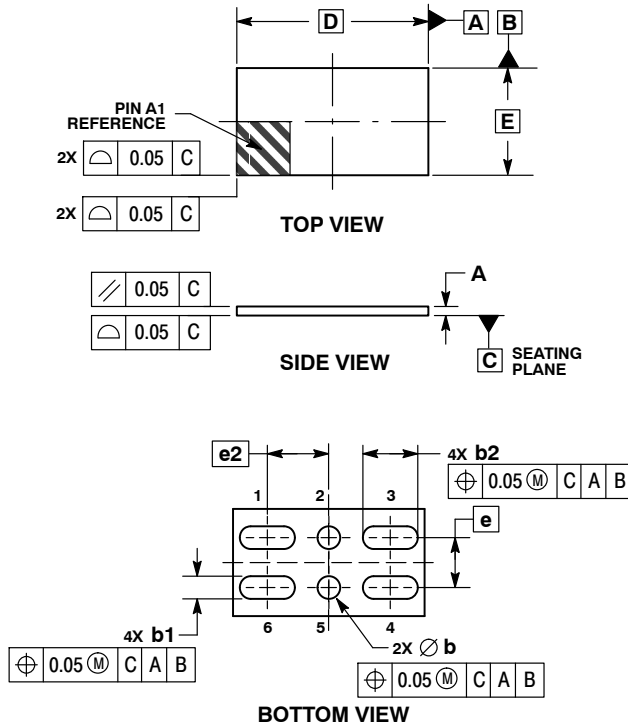




SCALE 4:1

**WLCSP6, 2.11x1.18x0.10**  
CASE 567NP  
ISSUE B

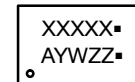
DATE 22 DEC 2016



## NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.

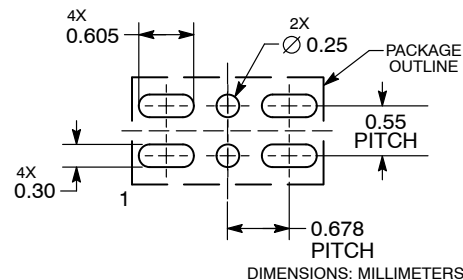
MILLIMETERS			
DIM	MIN	NOM	MAX
A	0.08	0.10	0.12
b	0.22	0.25	0.28
b1	0.27	0.30	0.33
b2	0.575	0.605	0.635
D	2.11 BSC		
E	1.18 BSC		
e	0.55 BSC		
e2	0.6775 BSC		

**GENERIC MARKING DIAGRAM\***


- A = Assembly Location
- Y = Year
- W = Work Week
- ZZ = Assembly Lot
- = Pb-Free Package

(Note: Microdot may be in either location)

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present.

**RECOMMENDED SOLDERING FOOTPRINT\***


\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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